Wire bonding

• What is wire bonding? (draw a figure)
• What are the advantages and disadvantage of using wire bonding?
• How many wire may be bonded on a chip?
Flip-chip bonding

• What is Flip chip bonding? (draw a figure)
• When was the Flip-chip bonding invented?
• What are the advantages and disadvantages?
• What is the limitation?
Stacked dies

• What is Stacked Dies? (draw a figure)
• What are the advantages of this method?
• What is the disadvantages?
• What are the differences between wires inside and outside of the chip?
Package-on-Package

• What is Package-on-Package? (draw a figure)
• What is the technique to make this package?
• What are the advantages and disadvantages?
• What are the limitations?
2.5D Packaging (not yet 3D)

• What is the 2.5D design? (draw a figure)
• What are the advantages and disadvantages?
• Maximum how many layers?
3D Through-Silicon-Via (TSV)

• What is TSV? (draw a figure)
• Comparing to wire, what are the differences?
• What are the advantages and disadvantages?
• Maximum how many layers?